

U.S. Serial No. 10/678,830
Filed: October 3, 2003

Examiner: Lee D. Wilson
Art Unit: 3723

LISTING OF CLAIMS

1-11 (canceled)

12. (New) A chemical mechanical polishing pad comprising an interior segment and an outer surface wherein the outer surface is at least 0.05 microns thick and wherein the outer surface comprises a metal film.
13. (New) A chemical mechanical polishing pad according to claim 13 wherein the metal film comprises a material selected from the group consisting of copper, copper oxide, tin, tin oxide and combinations of the foregoing.
14. (New) A chemical mechanical polishing pad according to claim 12 wherein the metal film is deposited by a means selected from the group consisting of vacuum metallization, sputtering and electroless plating.
15. (New) A chemical mechanical polishing pad according to claim 13 wherein the metal film is deposited by a means selected from the group consisting of vacuum metallization, sputtering, and electroless plating.
16. (New) A chemical mechanical polishing pad comprising an interior segment and an outer surface wherein the outer surface is at least 0.05 microns thick and wherein the outer surface is subjected to radiation selected from the group consisting of electron beam, ultraviolet and infra red and wherein the physical properties of the outer surface are modified by subjection to the radiation.